

## TIS/MADRID ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.1

MADRID ID: MD236674

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	ASSIGNS THE ENTIRE INTEREST AND THE GOODWILL	
<b>CONVEYING PARTY DATA</b>		
	<b>Name</b>	<b>Execution Date</b>
	Huawei Technologies Co., Ltd.	04/26/2021
<b>RECEIVING PARTY DATA</b>		
<b>Name:</b>	Honor Device Co., Ltd.	
<b>Address:</b>	Suite 3401, Unit A, Building 6, Shum Yip Sky Park, No. 8089, Hongli West Road, Xiangmihu Street, Futian District, Shenzhen 518040 Guangdong	
<b>Country:</b>	CN	
<b>Entity Type:</b>	Limited company	
<b>Entity Country:</b>	The People's Republic of China	
<b>PROPERTY NUMBERS Total: 1</b>		
	<b>Property Type</b>	<b>Number</b>
	<b>Serial Number:</b>	79252657
<b>CORRESPONDENCE DATA</b>		
<b>Correspondent Name:</b>	Honor Device Co., Ltd.	
<b>Address:</b>	Suite 3401, Unit A, Building 6, Shum Yip Sky Park, No. 8089, Hongli West Road, Xiangmihu Street, Futian District, Shenzhen 518040 Guangdong	
<b>Country:</b>	CN	

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